# SSM P/N CQF16401

CHIP CARRIER,
164 LEAD, .535 CAVITY

DWG. NO.
30916401

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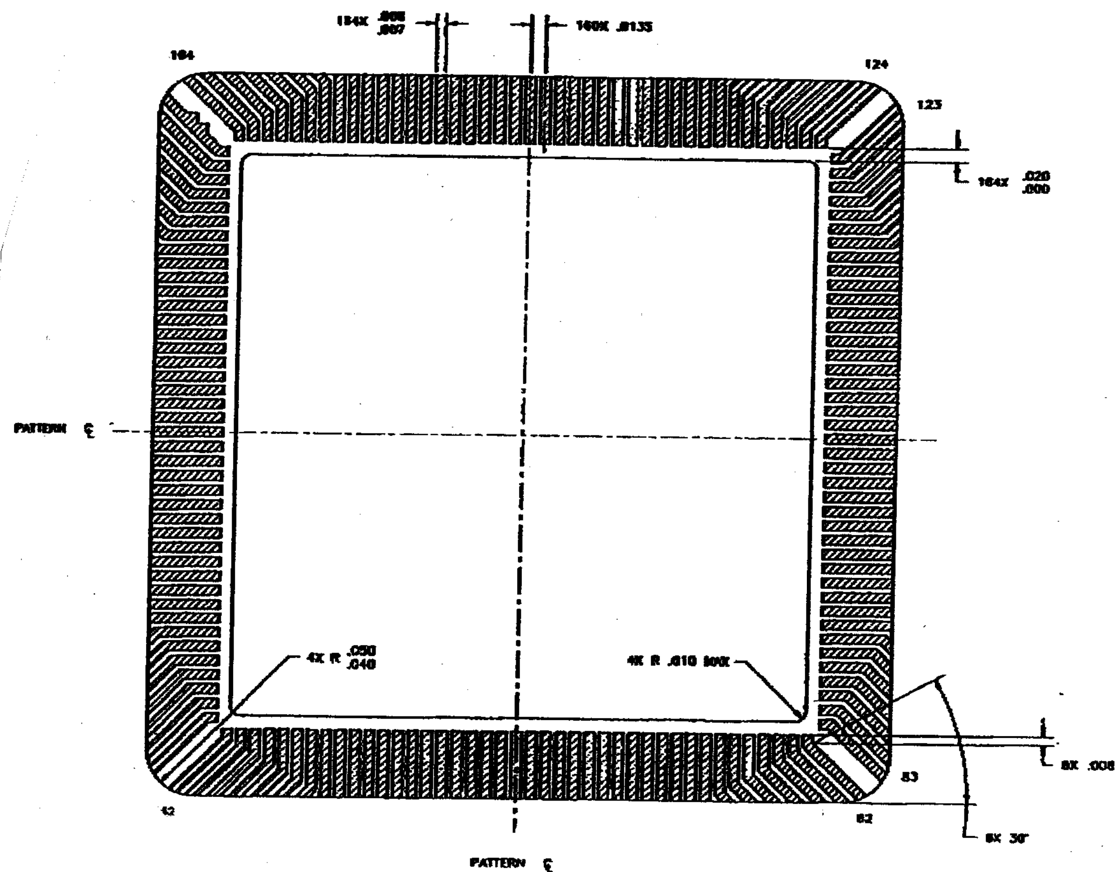


CAVITY DETAIL



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**PACKAGE SPECIFICATION: 164LD CQFP,.535 CAV.,.025 PITCH (SP164CQ.TXT, rev.1)**

I. Material:
  A. Substrate: Ceramic, 90-96% alumina, opaque.
  B. Metallization:
    1. Leads, external and internal: Must be Alloy 42 or approved equivalent.
  C. Sealing Glass.
    1. Glass compound shall be Owens Illinois CV-111.

II. Plating:(Base metal finish)
  A. Internal lead (wire bond posts) shall be Aluminum deposition.
    1. Thickness, 200 microinches (5.08 micrometers) minimum, 800 microinches (20.32 micrometers)maximum.
    2. Thickness shall be measured at the center of the lead (wire bond posts).

III. Metallization:
  A. No screened metallization will be done on this package.
    1. Die attach area is bare alumina.
    2. Seal ring area is bare alumina.

IV. Electrical:
  A. Lead Resistance:
    1. 0.30 ohms maximum.
    2. All leads.
    3. Measured from center of wire bond post to the lead, within .100" of the tip of the lead.

V. Mechanical:
  A. Package ceramic and sealing glass, must have no cracks, delaminations or foreign material visible at 20X.
  B. Assembled packages must pass the following tests per Mil-Std-883.
    1. Salt Atmosphere: Method 1009.6, condition A min.
    2. External Visual: Method 2009.8 (if not specifically mentioned elsewhere).
    3. Lead Integrity: Method 2004.5, condition B2.
  C. Coplanarity.
    1. Wire bond posts: .004"
      a. Measurement location; along post, from tip, +.004" to .015"; across post, 66% of width.

  D. External lead surface condition.
    1. The leads shall have no contaminent or condition that will inhibit a standard Sn (tin) plating process.

  E. Glass Seal.
    1. The glass shall be fired completely, to eliminate moisture release in subsequent process.
    2. The glass shall be fired such that any residual metallic material on the surface will not cause electrical bridging initially or after Sn (tin) plating.

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